



Aerospace and Defense Bumping Supplier Change: Virtex-4QV FPGA Space-Grade Devices Using Ceramic Flip Chip Column Grid Array (CF) Packages

XCN10006 (v1.0) April 19, 2010

Product Change Notice

Overview

The purpose of this notification is to announce that Xilinx has qualified a new bumping supplier for Virtex[®]-4QV FPGA space-grade devices in ceramic flip chip column grid array (CF) packages.

Description

Amkor Technology in Taiwan has been qualified to bump Virtex[®]-4QV FPGA space grade devices in ceramic flip chip column grid array (CF) packages. The bumping material set is high lead bumps (95%Pb/5%Sn) and is the same material set as Xilinx's current bumping vendor of Siliconware (SPIL) for these devices. Xilinx is making this change to ensure supply continuity as SPIL has discontinued their high lead bumping material set.

Amkor Technology in Taiwan's bumping line has been qualified and in production for Xilinx commercial plastic flip chip product since early 2000.

Products Affected

This change affects the following Virtex[®]-4QV FPGA space grade devices.

Table 1: Product Affected

Xilinx Product
XQR4VLX200-10CF1509V
XQR4VSX55-10CF1140V
XQR4VFX60-10CF1144V
XQR4VFX140-10CF1509V

Key Dates and Ordering Information

Table 2: Key date change for this PCN

Change	Implementation Date
Amkor Technology, Taiwan High Lead Bumping Production Ready	Date Code on or after 1032

Qualification Data

Table 3: Qualification results and report

Qualification Testing	Qualification Results	Qualification Report
Group A, B, C, D and E qualification and Temperature Cycle (Condition B) testing	Pass with no failures	RPT145

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Response

No response is required. For additional information or questions, please contact [Xilinx Technical Support](#).

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Additional Documentation

Qualification Report (RPT145):

<https://secure.xilinx.com/webreg/clickthrough.do?cid=144271>

Revision History

The following table shows the revision history for this document.

Date	Version	Revision
4/19/10	1.0	Initial release.

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